

**Please delete the present Abstract of the Disclosure.**

**Please add the following new Abstract of the Disclosure:**

An electroplating process of electroplating an electrically conductive substrate is described. The process includes electroplating intermittently to a predetermined plating thickness using the substrate surface as a cathode and a plating metal as an anode at a constant voltage between the anode and the cathode by repeating application of a voltage between a cathode and an anode and interruption of the application alternately. It is described that a voltage time/interruption time ratio is 0.1 to 1.0, a voltage time is not longer than 10 seconds, and an interruption time is not less than  $1 \times 10^{-12}$  seconds.